ne<mark>x</mark>peria

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In data sheets and application notes which still contain NXP or Philips Semiconductors references, use the references to Nexperia, as shown below.

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Should be replaced with:

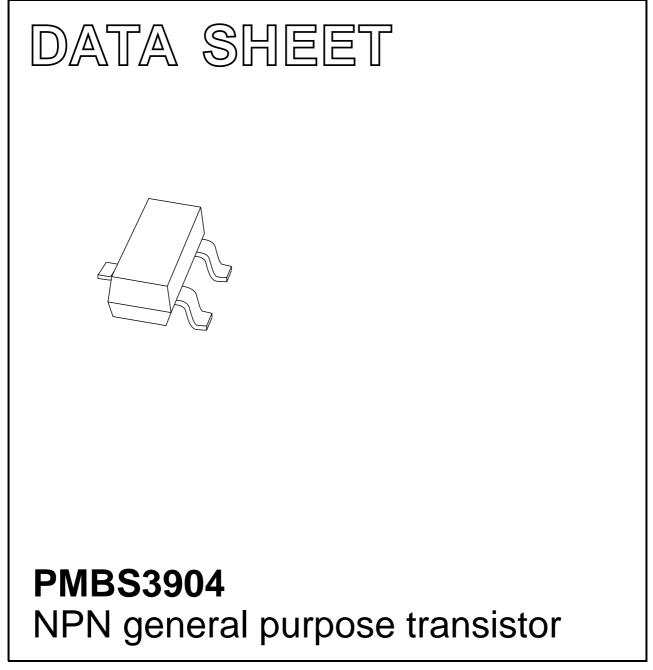
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 Apr 22 2004 Feb 02



FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 40 V).

APPLICATIONS

• General purpose switching and amplification, e.g. telephony and professional communication equipment.

DESCRIPTION

NPN transistor in a plastic SOT23 package. PNP complement: PMBS3906.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PMBS3904	*O4

Note

1. * = p: Made in Hong Kong.

* = t : Made in Malaysia.

* = W : Made in China.

ORDERING INFORMATION

TYPE PACKAGE NUMBER NAME DESCRIPTION VERSION PMBS3904 plastic surface mounted package; 3 leads SOT23

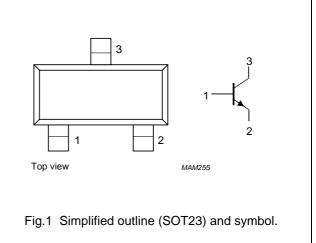
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	60	V
V _{CEO}	collector-emitter voltage	open base	-	40	V
V _{EBO}	emitter-base voltage	open collector	-	6	V
I _C	collector current capability		-	100	mA
I _{CM}	peak collector current		-	200	mA
I _{BM}	peak base current		-	200	mA
P _{tot}	total power dissipation $T_{amb} \le 25 \text{ °C}$		-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



PMBS3904

PMBS3904

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

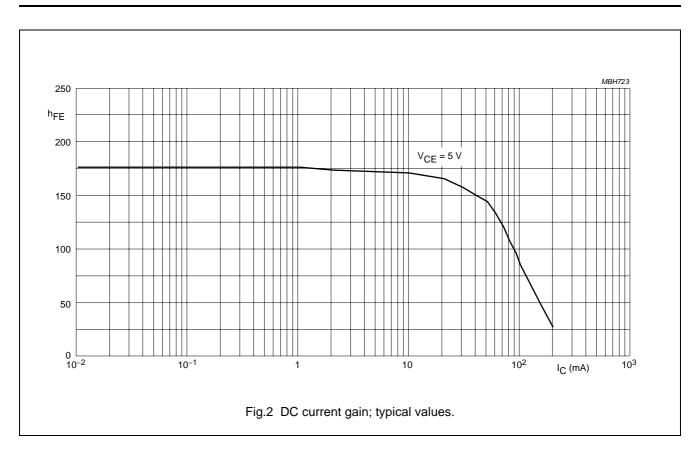
CHARACTERISTICS

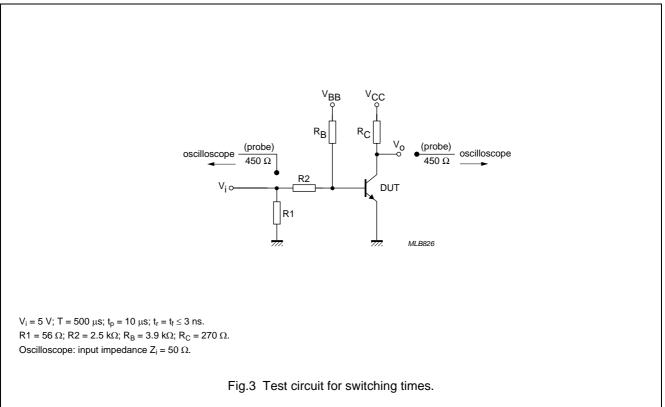
 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 30 V	_	50	nA
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = 5 V	_	50	nA
h _{FE}	DC current gain	V _{CE} = 1 V; note 1; (see Fig.2)			
		I _C = 0.1 mA	40	_	
		$I_{\rm C} = 1 \rm{mA}$	70	_	
		I _C = 10 mA	100	300	
		I _C = 50 mA	60	_	
		I _C = 100 mA	30	_	
V _{CEsat}	collector-emitter saturation	I _C = 10 mA; I _B = 1 mA	_	200	mV
vo	voltage	$I_{\rm C} = 50 \text{ mA}; I_{\rm B} = 5 \text{ mA}$	_	300	mV
V _{BEsat} b	base-emitter saturation voltage	I _C = 10 mA; I _B = 1 mA	650	850	mV
		$I_{\rm C} = 50 \text{ mA}; I_{\rm B} = 5 \text{ mA}$	_	950	mV
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = 5 V; f = 1 MHz$	-	4	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V; f = 1 MHz$	-	12	pF
f _T	transition frequency	$I_{C} = 10 \text{ mA}; V_{CE} = 20 \text{ V}; f = 100 \text{ MHz}$	180	_	MHz
F	noise figure	I_{C} = 100 μA; V _{CE} = 5 V; R _S = 1 kΩ; f = 10 Hz to 15.7 kHz	_	5	dB
Switching t	imes (between 10% and 90% leve	els); (see Fig.3)			
on	turn-on time	$I_{Con} = 10 \text{ mA}; I_{Bon} = 1 \text{ mA}; I_{Boff} = -1 \text{ mA}; V_{CC} = 3 \text{ V}; V_{BB} = -1.9 \text{ V}$	_	110	ns
t _d	delay time		_	50	ns
tr	rise time		_	60	ns
off	turn-off time]	-	1200	ns
S	storage time]	_	1000	ns
t _f	fall time	1	_	200	ns

Note

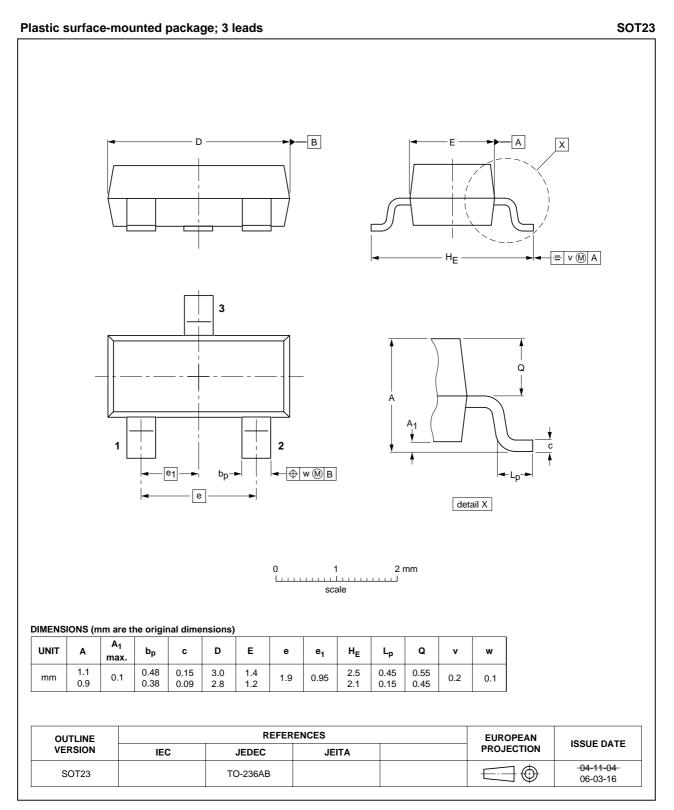
1. Pulse test: $t_p \leq 300~\mu\text{s};~\delta \leq 0.02.$





PMBS3904

PACKAGE OUTLINE



PMBS3904

PMBS3904

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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